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Applicant: Fisher et al.

Serial No.: 09/705,466

Filed: 11/03/2000

For: ENCAPSULATION FOR PARTICLE ENTRAPMENT

AMENDMENT

3 July 2002

Assistant Commissioner for Patents
Washington, DC 20231

Art Unit: 2828

Examiner: Thai, Luan C. T. / 26/02

Docket No. TI-24980

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MAILING CERTIFICATE UNDER 37 C.F.R. §1.8(A)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231 on the date shown below.

Charles A. Brill

7-3-2002

Date

Dear Sir:

In response to the Examiner's Action mailed 3 April 2002, applicant amends as follows:

In the claims:

Please amend Claims 1 and 2 as follows:

1. (amended) A method of protecting debris-intolerant micromechanical devices, said method comprising:

attaching a device to a package substrate, said device having at least one debris-generating region, and at least one debris-intolerant region;

encapsulating at least one of said debris-generating regions with a blocking material, said blocking material avoiding contact with said debris-intolerant region;

and

attaching a package lid to said package substrate, to enclose said device and said blocking material.

2. (amended) The method of Claim 1, said attaching step further comprising:

attaching a device to a substrate, said device having at least one said debris-generating region comprising a sidewall.

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REMARKS

This application was originally filed on 3 November 2000 with sixteen claims, two of which were written in independent form. Claims 11-16 have been withdrawn from consideration. Claims 1-10 have been rejected. No claims have been allowed.

Claims 1 and 2 have been amended to broaden their scope. In Claim 1, the limitation "which source debris over the lifetime of said device" was deleted. In Claim 2, the limitation "formed where said device was attached to a wafer" was deleted.

The drawings were objected to under 37 C.F.R. § 1.83(a) for failing to show every feature of the invention specified in the claims. Specifically, the Examiner objected to the lack of a drawing for the feature "the device was attached to the wafer." Claim 2 was rejected under 35 U.S.C. § 112, first paragraph, for containing subject matter which was not described in such a way as to enable one skilled in the art to make and use the invention. The applicant has broadened Claim 2 by deleting the phrase "formed where said device was attached to a wafer" to overcome the rejection of Claim 2 under 35 U.S.C. § 112, first paragraph, and the objection under 37 C.F.R. § 1.83(a) to the drawings.

Claim 1 was rejected under 35 U.S.C. § 103(a) as being unpatentable over U.S. Patent No. 6,117,705 to Glenn et al. ("Glenn"). The applicant respectfully disagrees. Glenn does not show, teach, or suggest "attaching a package lid to said package substrate, to enclose said device and said blocking material" as recited by amended Claim 1.

Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned "Version With Markings To Show Changes Made."

In view of the amendments and the remarks presented herewith, it is believed that the claims currently in the application, Claims 1-10, accord with the requirements of 35 U.S.C. § 112 and are allowable over the prior art of record. Therefore, it is urged that Claims 1-10 are in condition for allowance. Reconsideration of the present application is respectfully requested.

Respectfully submitted,



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